Vishay General Semiconductor

Glass Passivated Ultrafast Rectifier



Glass encapsulation technique is covered by Patent No. 3 996 602 brazed-lead assembly to Patent No. 3,930,306

DO-204AL (DO-41)

1.0 A

600 V

30 A

30 ns

1.3 V

175 °C

FEATURES

- Cavity-free glass-passivated junction
- · Ideal for printed circuit boards
- · Ultrafast reverse recovery time
- Low forward voltage drop
- Low leakage current
- Low switching losses, high efficiency
- High forward surge capability
- Meets environmental standard MIL-S-19500
- Solder dip 275 °C max. 10 s, per JESD 22-B106
- AEC-Q101 qualified
- · Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

TYPICAL APPLICATIONS

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer, computer and telecommunication.

Case: DO-204AL, molded plastic over glass body Molding compound meets UL 94 V-0 flammability rating Base P/N-E3 - RoHS compliant, commercial grade Base P/NHE3 - RoHS compliant, AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 1A whisker test. HE3 suffix

Polarity: Color band denotes cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Maximum repetitive peak reverse voltage	V _{RRM}	600	V			
Maximum RMS voltage	V _{RMS}	V _{RMS} 420				
Maximum DC blocking voltage	V _{DC}	600	V			
Maximum average forward rectified current 0.375" (9.5 mm) lead length at T_L = 85 $^\circ C$ (fig. 1)	I _{F(AV)}	1.0	А			
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM} 30		A			
Non repetitive peak reverse energy	E _{RSM} ⁽¹⁾	5.0	mJ			
Operating junction and storage temperature range	T _J , T _{STG}	- 65 to + 175	°C			

Note

(1) Peak reverse energy measured with 8/20 µs surge





I_{F(AV)} V_{RRM}

I_{FSM}

t_{rr}

 V_{F}

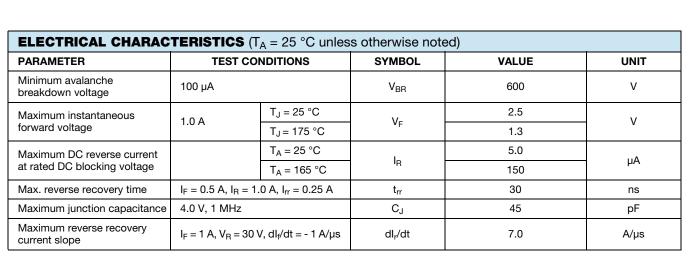
T_J max.

PRIMARY CHARACTERISTICS

MECHANICAL DATA

meets JESD 201 class 2 whisker test

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THERMAL CHARACTERISTICS ($T_A = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Typical thermal resistance	$R_{\theta JA}^{(1)}$	70	°C/W			
	R _{θJL} ⁽²⁾	16				

Notes

(1) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, mounted on P.C.B. with 0.5" x 0.5" (12 mm x 12 mm) copper pads

⁽²⁾ Thermal resistance from junction to lead at 0.375" (9.5 mm) lead length with both leads attached to heatsink

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
SBYV26C-E3/54	0.339	54	5500	13" diameter paper tape and reel		
SBYV26C-E3/73	0.339	73	3000	Ammo pack packaging		
SBYV26CHE3/54 (1)	0.339	54	5500	13" diameter paper tape and reel		
SBYV26CHE3/73 (1)	0.339	73	3000	Ammo pack packaging		

Note

⁽¹⁾ AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

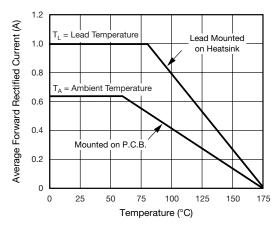


Fig. 1 - Maximum Forward Current Derating Curve

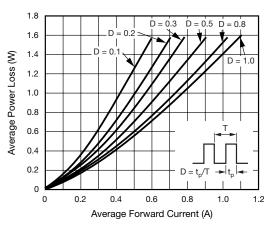


Fig. 2 - Forward Power Loss Characteristics

For technical questions within your region, please contact one of the following: <u>DiodesAmericas@vishay.com</u>, <u>DiodesAsia@vishay.com</u>, <u>DiodesEurope@vishay.com</u>



SBYV26C

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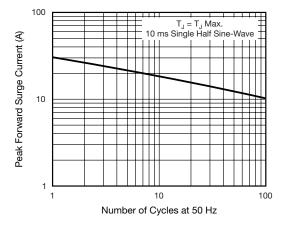


Fig. 3 - Maximum Non-Repetitive Peak Forward Surge Current

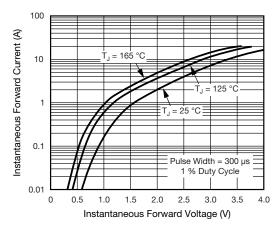


Fig. 4 - Typical Instantaneous Forward Characteristics

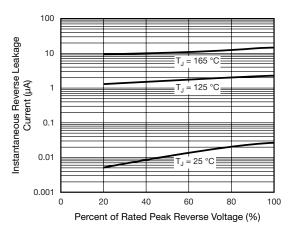


Fig. 5 - Typical Reverse Leakage Characteristics

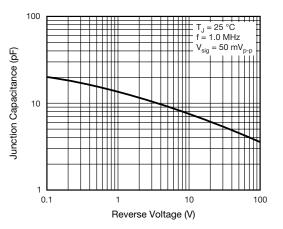


Fig. 6 - Typical Junction Capacitance

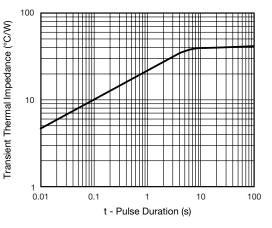
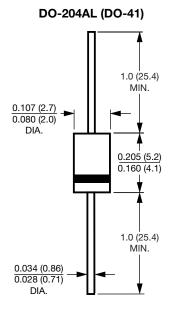


Fig. 7 - Typical Transient Thermal Impedance

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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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